



### 3-331272-4 Product Details



**3-331272-4**

TE Internal Number: 3-331272-4

Active

View 3D PDF

#### Discrete Sockets

Always EU RoHS/ELV Compliant (Statement of Compliance)

#### Product Highlights:

- Mini-Spring Socket Product Line
- Board-to-Board, Wire-to-Board
- Applies To Wire/Cable, Applies To Printed Circuit Board
- Contact - Rated Current = 5 A
- Wire/Cable Size = .205 - .258 mm<sup>2</sup>

#### Documentation & Additional Information

##### Product Drawings:

- [MINIATURE SPRING SOCKET ASSEMBLY, SERIES 2](#) (PDF, English)

##### Catalog Pages/Data Sheets:

- None Available

##### Product Specifications:

- None Available

##### Application Specifications:

- None Available

##### Instruction Sheets:

- None Available

##### CAD Files: (CAD Format & Compression Information)

- [2D Drawing](#) (DXF, Version AS1)
- [3D Model](#) (IGES, Version AS1)
- [3D Model](#) (STEP, Version AS1)

##### Additional Information:

- [Product Line Information](#)

##### Related Products:

- [Tooling](#)

#### Product Features (Please use the Product Drawing for all design activity)

##### Product Type Features:

- Product Line = Mini-Spring Socket
- **Socket Length (mm [in])** = 3.51 [0.138]
- **Recommended Hole Size (mm [in])** = 1.32 [0.052]
- **Sleeve Style** = Knockout Bottom
- **Sealant** = Without
- **Wire/Cable Type** = Discrete Wire
- **Termination Method to Wire/Cable** = Solder
- **Termination Method to PC Board** = Through Hole - Press Fit
- **Product Series** = 3
- **Sleeve Material** = Copper
- **Profile** = Zero

##### Electrical Characteristics:

- **Contact - Rated Current (A)** = 5

##### Termination Features:

- **Wire/Cable Size (mm<sup>2</sup>)** = 0.205 - 0.258
- **Wire/Cable Size (AWG)** = 23 - 24
- **Insertion Method** = Hand/Semi-Automatic

##### Body Features:

- **Mating Pin Dia. Range (mm [in])** = 0.56 - 0.64 [0.022 - 0.025]
- **Sleeve Material Plating** = Gold Flash over Nickel
- **Wire Tvpne** = Solid

##### Industry Standards:

- **Government/Industry Qualification** = No
- **RoHS/ELV Compliance** = RoHS compliant, ELV compliant
- **Lead Free Solder Processes** = Wave solder capable to 260°C, Wave solder capable to 240°C, Wave solder capable to 265°C, Reflow solder capable to 245°C, Reflow solder capable to 260°C, Pin-in-Paste capable to 245°C, Pin-in-Paste capable to 260°C
- **RoHS/ELV Compliance History** = Always was RoHS compliant

##### Environmental:

- **Operating Temperature (°C [°F])** = -65 - +126 [-85 - +258]

##### Conditions for Usage:

- **Applies To** = Wire/Cable, Printed Circuit Board
- **PCB Thickness, Recommended (mm [in])** = 0.79 - 3.18 [0.031 - 0.125]

##### Operation/Application:

- **Application Use** = Board-to-Board, Wire-to-Board
- **Contact Transmits (Typical Application)** = Signal (Data)/Power
- **Application** = Production

##### Packaging Features:

- **Packaging Method** = Loose Piece
- **Packaging Quantity** = 2,000/Bag

- Spring Material = Beryllium Copper

**Other:**

- Brand = AMP

**Contact Features:**

- Contact Spring Plating = Gold (30)
- Contact Plating, Mating Area, Material = Gold (30)
- Contact Plating, Mating Area, Thickness ( $\mu\text{m}$  [ $\mu\text{in}$ ]) = 0.00076 [0.03]
- Contact Type = Socket
- Contact Base Material = Beryllium Copper